Client Ref.: GNC26US; Atty. Dkt.: 081498-0306614

I claim:

1. A microchip comprising:

a plurality of dies, each made by a separate fabrication process and assembled into a package with the separate die sections connected directly.

2. The microchip according to claim 1, wherein the separate die sections are connected by interconnects that are widened compared to the circuits of the die.